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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XF

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	17
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv32ka301-e-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

TABLE 4-4: ICN REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNPD1	0056	CN15PDE ⁽¹⁾	CN14PDE	CN13PDE	CN12PDE	CN11PDE	CN10PDE ^(1,2)	CN9PDE ⁽¹⁾	CN8PDE ⁽³⁾	CN7PDE ⁽¹⁾	CN6PDE	CN5PDE	CN4PDE	CN3PDE	CN2PDE	CN1PDE	CN0PDE	0000
CNPD2	0058	CN31PDE ^(1,2)	CN30PDE	CN29PDE	CN28PDE ^(1,2)	CN27PDE ⁽¹⁾	CN26PDE ^(1,2)	CN25PDE ^(1,2)	CN24PDE ⁽¹⁾	CN23PDE	CN22PDE	CN21PDE	CN20PDE ^(1,2)	CN19PDE ^(1,2)	CN18PDE ^(1,2)	CN17PDE ^(1,2)	CN16PDE ⁽¹⁾	0000
CNPD3	005A	_	-	_	_	_	_	_	_	_	-	_	CN36PDE ^(1,2)	CN35PDE ^(1,2)	CN34PDE ^(1,2)	CN33PDE ^(1,2)	CN32PDE ^(1,2)	0000
CNEN1	0062	CN15IE ⁽¹⁾	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE ^(1,2)	CN9IE ⁽¹⁾	CN8IE ⁽³⁾	CN7IE ⁽¹⁾	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	0064	CN31IE ^(1,2)	CN30IE	CN29IE	CN28IE ^(1,2)	CN27IE ⁽¹⁾	CN26IE ^(1,2)	CN25IE ^(1,2)	CN24IE ⁽¹⁾	CN23IE	CN22IE	CN21IE	CN20IE ^(1,2)	CN19IE ^(1,2)	CN18IE ^(1,2)	CN17IE ^(1,2)	CN16IE ⁽¹⁾	0000
CNEN3	0066	—	_		—		_	-	-	_	_	_	CN36IE ^(1,2)	CN35IE ^(1,2)	CN34IE ^(1,2)	CN33IE ^(1,2)	CN32IE ^(1,2)	0000
CNPU1	006E	CN15PUE ⁽¹⁾	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE ^(1,2)	CN9PUE ⁽¹⁾	CN8PUE ⁽³⁾	CN7PUE ⁽¹⁾	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CNOPUE	0000
CNPU2	0070	CN31PUE ^(1,2)	CN30PUE	CN29PUE	CN28PUE ^(1,2)	CN27PUE ⁽¹⁾	CN26PUE ^(1,2)	CN25PUE ^(1,2)	CN24PUE ⁽¹⁾	CN23PUE	CN22PUE	CN21PUE	CN20PUE ^(1,2)	CN19PUE ^(1,2)	CN18PUE ^(1,2)	CN17PUE ^(1,2)	CN16PUE ⁽¹⁾	0000
CNPU3	0072	—	_		—		_	-	-	_	_	_	CN36PUE ^(1,2)	CN35PUE ^(1,2)	CN34PUE ^(1,2)	CN33PUE ^(1,2)	CN32PUE ^(1,2)	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: These bits are not implemented in 20-pin devices.

2: These bits are not implemented in 28-pin devices.

3: These bits are not implemented in FV devices.

TABLE 4-24: NVM REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets ⁽¹⁾
NVMCON	0760	WR	WREN	WRERR	PGMONLY	_	—	—	—	—	ERASE	NVMOP5	NVMOP4	NVMOP3	NVMOP2	NVMOP1	NVMOP0	0000
NVMKEY	0766	_	—		—			-	_				NVM	KEY				0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal. Note 1: Reset value shown is for POR only. The value on other Reset states is dependent on the state of memory write or erase operations at the time of Reset.

TABLE 4-25: ULTRA LOW-POWER WAKE-UP REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ULPWCON	0768	ULPEN	—	ULPSIDL	—	—	_		ULPSINK		-	_	_	—	—	_		0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-26: PMD REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770	T5MD	T4MD	T3MD	T2MD	T1MD	—	—	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	ADC1MD	0000
PMD2	0772	_	_	_	_	_	IC3MD	IC2MD	IC1MD	_	_	_	_	_	OC3MD	OC2MD	OC1MD	0000
PMD3	0774	_	_	_	_	_	CMPMD	RTCCMD	_	CRCPMD	_	_	_	_	_	I2C2MD	_	0000
PMD4	0776	-	_		—	_		—	—	ULPWUMD	—	_	EEMD	REFOMD	CTMUMD	HLVDMD	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

6.4.3 READING THE DATA EEPROM

To read a word from data EEPROM, the table read instruction is used. Since the EEPROM array is only 16 bits wide, only the TBLRDL instruction is needed. The read operation is performed by loading TBLPAG and WREG with the address of the EEPROM location, followed by a TBLRDL instruction.

A typical read sequence, using the Table Pointer management (builtin_tblpage and builtin_tbloffset) and table read procedures (builtin_tblrdl) from the C30 compiler library, is provided in Example 6-5.

Program Space Visibility (PSV) can also be used to read locations in the data EEPROM.

EXAMPLE 6-5: READING THE DATA EEPROM USING THE TBLRD COMMAND

```
int attribute ((space(eedata))) eeData = 0x1234;
                                          // Data read from EEPROM
int data;
/*_____
                                       _____
The variable eeData must be a Global variable declared outside of any method
the code following this comment can be written inside the method that will execute the read
_____
*/
  unsigned int offset;
   \ensuremath{//} Set up a pointer to the EEPROM location to be erased
  TBLPAG = __builtin_tblpage(&eeData);
                                           // Initialize EE Data page pointer
  offset = __builtin_tbloffset(&eeData);
data = __builtin_tblrdl(offset);
                                            // Initizlize lower word of address
                                            // Write EEPROM data to write latch
```

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 7	CLKLOCK: Clock Selection Lock Enabled bit	
	If FSCM is enabled (FCKSM1 = <u>1):</u>	
	1 = Clock and PLL selections are locked	
	0 = Clock and PLL selections are not locked and may be modified by setting the OSWEN bit	
	If FSCM is disabled (FCKSM1 = 0):	
	Clock and PLL selections are never locked and may be modified by setting the OSWEN bit.	
bit 6	Unimplemented: Read as '0'	
bit 5	LOCK: PLL Lock Status bit ⁽²⁾	
	1 = PLL module is in lock or PLL module start-up timer is satisfied	
	0 = PLL module is out of lock, PLL start-up timer is running or PLL is disabled	
bit 4	Unimplemented: Read as '0'	
bit 3	CF: Clock Fail Detect bit	
	1 = FSCM has detected a clock failure	
	0 = No clock failure has been detected	
bit 2	SOSCDRV: Secondary Oscillator Drive Strength bit ⁽³⁾	
	1 = High-power SOSC circuit is selected	
	0 = Low/high-power select is done via the SOSCSRC Configuration bit	
bit 1	SOSCEN: 32 kHz Secondary Oscillator (SOSC) Enable bit	
	1 = Enables the secondary oscillator	
	0 = Disables the secondary oscillator	
bit 0	OSWEN: Oscillator Switch Enable bit	
	1 = Initiates an oscillator switch to the clock source specified by the NOSC<2:0> bits	
	0 = Oscillator switch is complete	
Note 1:	Reset values for these bits are determined by the FNOSCx Configuration bits.	

- 2: This bit also resets to '0' during any valid clock switch or whenever a non-PLL Clock mode is selected.
 - **3:** When SOSC is selected to run from a digital clock input, rather than an external crystal (SOSCSRC = 0), this bit has no effect.

10.4 Voltage Regulator-Based Power-Saving Features

The PIC24FV32KA304 series devices have a Voltage Regulator that has the ability to alter functionality to provide power savings. The on-board regulator is made up of two basic modules: the Voltage Regulator (VREG) and the Retention Regulator (RETREG). With the combination of VREG and RETREG, the following power modes are available:

10.4.1 RUN MODE

In Run mode, the main VREG is providing a regulated voltage with enough current to supply a device running at full speed, and the device is not in Sleep or Deep Sleep Mode. The Retention Regulator may or may not be running, but is unused.

10.4.2 SLEEP (STANDBY) MODE

In Sleep mode, the device is in Sleep and the main VREG is providing a regulated voltage at a reduced (standby) supply current. This mode provides for limited functionality due to the reduced supply current. It requires a longer time to wake-up from Sleep.

10.4.3 RETENTION SLEEP MODE

In Retention Sleep mode, the device is in Sleep and all regulated voltage is provided solely by the Retention Regulator. Consequently, this mode has lower power consumption than regular Sleep mode, but is also limited in terms of how much functionality can be enabled. Retention Sleep wake-up time is longer than Sleep mode due to the extra time required to raise the VCORE supply rail back to normal regulated levels.

Note: PIC24F32KA30X family devices do not use an On-Chip Voltage Regulator, so they do not support Retention Sleep mode.

10.4.4 DEEP SLEEP MODE

In Deep Sleep mode, both the main Voltage Regulator and Retention Regulator are shut down, providing the lowest possible device power consumption. However, this mode provides no retention or functionality of the device and has the longest wake-up time.

		VICES		
RETCGF Bit (FPOR<2>)	RETEN Bit (RCON<12>	PMSLP Bit (RCON<8>)	Power Mode During Sleep	Description
0	0	1	Sleep	VREG mode (normal) is unchanged during Sleep. RETREG is unused.
0	0	0	Sleep (Standby)	VREG goes to Low-Power Standby mode during Sleep. RETREG is unused.
0	1	0	Retention Sleep	VREG is off during Sleep. RETREG is enabled and provides Sleep voltage regulation.
1	х	1	Sleep	VREG mode (normal) is unchanged during Sleep. RETREG is disabled at all times.
1	х	0	Sleep (Standby)	VREG goes to Low-Power Standby mode during Sleep. RETREG is disabled at all times

TABLE 10-1:VOLTAGE REGULATION CONFIGURATION SETTINGS FOR PIC24FV32KA304
FAMILY DEVICES

REGISTER 11-2: ANSB: ANALOG SELECTION (PORTB)

R/W-1	R/W-1	R/W-1	R/W-1	U-0	U-0	U-0	U-0
ANSB15	ANSB14	ANSB13	ANSB12	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	ANSB4	ANSB3 ⁽¹⁾	ANSB2	ANSB1	ANSB0
bit 7							bit 0

Legend:

bit 7

Legena:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 ANSB<15:12>: Analog Select Control bits

- 1 = Digital input buffer is not active (use for analog input)
- 0 = Digital input buffer is active
- bit 11-5 Unimplemented: Read as '0'
- bit 4-0 ANSB<4:0>: Analog Select Control bits⁽¹⁾
 - 1 = Digital input buffer is not active (use for analog input)
 - 0 = Digital input buffer is active
- Note 1: The ANSB3 bit is not available on 20-pin devices.

REGISTER 11-3: ANSC ANALOG SELECTION (PORTC)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
_	—	—	—	—	ANSC2 ⁽¹⁾	ANSC1 ⁽¹⁾	ANSC0 ⁽¹⁾

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-3 Unimplemented: Read as '0'

bit 2-0 ANSC<2:0>: Analog Select Control bits⁽¹⁾

- 1 = Digital input buffer is not active (use for analog input)
- 0 = Digital input buffer is active

Note 1: These bits are not available on 20-pin or 28-pin devices.

bit 0

15.0 OUTPUT COMPARE WITH DEDICATED TIMERS

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, Section 35. "Output Compare with Dedicated Timer" (DS39723).

All devices in the PIC24FV32KA304 family feature 3 independent output compare modules. Each of these modules offers a wide range of configuration and operating options for generating pulse trains on internal device events. Also, the modules can produce Pulse-Width Modulated (PWM) waveforms for driving power applications.

Key features of the output compare module include:

- Hardware-configurable for 32-bit operation in all modes by cascading two adjacent modules
- Synchronous and Trigger modes of output compare operation, with up to 21 user-selectable Sync/trigger sources available
- Two separate Period registers (a main register, OCxR, and a secondary register, OCxRS) for greater flexibility in generating pulses of varying widths
- Configurable for single pulse or continuous pulse generation on an output event, or continuous PWM waveform generation
- Up to 6 clock sources available for each module, driving a separate internal 16-bit counter

15.1 General Operating Modes

15.1.1 SYNCHRONOUS AND TRIGGER MODES

By default, the output compare module operates in a Free-Running mode. The internal 16-bit counter, OCxTMR, counts up continuously, wrapping around from FFFFh to 0000h on each overflow, with its period synchronized to the selected external clock source. Compare or PWM events are generated each time a match between the internal counter and one of the Period registers occurs.

In Synchronous mode, the module begins performing its compare or PWM operation as soon as its selected clock source is enabled. Whenever an event occurs on the selected Sync source, the module's internal counter is reset. In Trigger mode, the module waits for a Sync event from another internal module to occur before allowing the counter to run.

Free-Running mode is selected by default or any time that the SYNCSELx bits (OCxCON2<4:0>) are set to '00000'. Synchronous or Trigger modes are selected any time the SYNCSELx bits are set to any value except '00000'. The OCTRIG bit (OCxCON2<7>) selects either Synchronous or Trigger mode. Setting this bit selects Trigger mode operation. In both modes, the SYNCSELx bits determine the Sync/trigger source.

15.1.2 CASCADED (32-BIT) MODE

By default, each module operates independently with its own set of 16-bit Timer and Duty Cycle registers. To increase the range, adjacent even and odd numbered modules can be configured to function as a single 32-bit module. (For example, Modules 1 and 2 are paired, as are Modules 3 and 4, and so on.) The odd numbered module (OCx) provides the Least Significant 16 bits of the 32-bit register pairs, and the even numbered module (OCy) provides the Most Significant 16 bits. Wraparounds of the OCx registers cause an increment of their corresponding OCy registers.

Cascaded operation is configured in hardware by setting the OC32 bit (OCxCON2<8>) for both modules.

REGISTER 16-1: SPIx STAT: SPIx STATUS AND CONTROL REGISTER (CONTINUED)

- bit 1 SPITBF: SPIx Transmit Buffer Full Status bit
 - 1 = Transmit has not yet started, SPIxTXB is full
 - 0 = Transmit has started, SPIxTXB is empty

In Standard Buffer mode:

Automatically set in hardware when the CPU writes the SPIxBUF location, loading SPIxTXB. Automatically cleared in hardware when the SPIx module transfers data from SPIxTXB to SPIxSR.

In Enhanced Buffer mode:

Automatically set in hardware when the CPU writes the SPIxBUF location, loading the last available buffer location. Automatically cleared in hardware when a buffer location is available for a CPU write.

bit 0 SPIRBF: SPIx Receive Buffer Full Status bit

- 1 = Receive is complete, SPIxRXB is full
- 0 = Receive is not complete, SPIxRXB is empty

In Standard Buffer mode:

Automatically set in hardware when the SPIx transfers data from the SPIxSR to SPIxRXB. Automatically cleared in hardware when the core reads the SPIxBUF location, reading SPIxRXB.

In Enhanced Buffer mode:

Automatically set in hardware when SPIx transfers data from SPIxSR to buffer, filling the last unread buffer location. Automatically cleared in hardware when a buffer location is available for a transfer from SPIxSR.

19.2.4 RTCC CONTROL REGISTERS

REGISTER 19-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER⁽¹⁾

R/W-0	U-0	R/W-0	R-0, HSC	R-0, HSC	R/W-0	R/W-0	R/W-0
RTCEN ⁽²⁾	_	RTCWREN	RTCSYNC	HALFSEC ⁽³⁾	RTCOE	RTCPTR1	RTCPTR0
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CAL7	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0
bit 7	L	L				L	bit 0
Legend:		HSC = Hardw	are Settable/C	learable bit			
R = Readable	bit	W = Writable	bit	U = Unimplem	nented bit, read	l as '0'	
-n = Value at I	POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkr	iown
bit 15	RTCEN: RTC	C Enable bit ⁽²⁾					
	1 = RTCC mo	odule is enable	d				
bit 11			:0 				
DIL 14			, aiotoro Mrito E				
DIL 13	1 = RTCVAL	H and RTCVAL	I registers car	hable bli	w the user		
	0 = RTCVAL	H and RTCVAL	L registers are	locked out from	n being written	to by the user	
bit 12	RTCSYNC: R	TCC Value Re	gisters Read S	ynchronization	bit	-	
	1 = RTCVAL	H, RTCVALL ar	d ALCFGRPT	registers can c	hange while re	ading due to a	rollover ripple
	resulting	in an invalid da	ta read. If the r	register is read	twice and resu	Its in the same	data, the data
		ssumed to be v	alid.	egisters can be	read without o	oncern over a	rollover ripple
bit 11		alf Second Stat	ALCIGINI IN	egisters can be		oncent over a	
bit II	1 = Second h	alf period of a	second				
	0 = First half	period of a sec	ond				
bit 10	RTCOE: RTC	C Output Enab	le bit				
	1 = RTCC ou	tput is enabled					
	0 = RTCC ou	tput is disabled	l				
bit 9-8	RTCPTR<1:0	>: RTCC Value	Register Wind	dow Pointer bits	S		
	Points to the c	orresponding ה <1.0> value dec	CICC Value reg	gisters when rea	ading the RTCV	ALH and RTC	/ALL registers.
	RTCVAI <15:8	3>:		cry read of white	C OF ICT O WALL		00.
	00 = MINUTES						
	01 = WEEKDAY						
	10 = MONTH						
	RTC/AI < 7.0>						
	00 = SECONI						
	01 = HOURS						
	10 = DAY 11 = YFAR						

Note 1: The RCFGCAL register is only affected by a POR.

- 2: A write to the RTCEN bit is only allowed when RTCWREN = 1.
- **3:** This bit is read-only; it is cleared to '0' on a write to the lower half of the MINSEC register.

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0
bit 7							bit 0
R = Readable	a hit	W = Writable	hit	II = I Inimplen	nented hit rea	n, se p	
-n = Value at	POR	$(1)^{2} = \text{Rit is set}$	bit	$0^{\circ} = \text{Bit is clear}$	ared	x = Bit is unkr	lown
ii valae at							
bit 15	ALRMEN: Ala	arm Enable bit					
	1 = Alarm is	enabled (clear	ed automatica	illy after an ala	irm event whe	never ARPT<7	:0> = 00h and
	CHIME =	= 0) disabled					
hit 14		ne Enable bit					
511 14	1 = Chime is	enabled: ARP	T<7:0> bits are	allowed to roll	over from 00h	to FFh	
	0 = Chime is	disabled; ARP	T<7:0> bits sto	op once they real	ach 00h		
bit 13-10	AMASK<3:0>	>: Alarm Mask	Configuration b	oits			
	0000 = Ever	ry half second					
	0001 = Ever	ry second					
	0010 - Ever	ry minute					
	0100 = Ever	ry 10 minutes					
	0101 = Ever	ry hour					
	0110 = Onco	e a day e a week					
	1000 = Onc	e a month					
	1001 = Once	e a year (excep	ot when configu	ured for Februa	ry 29 th , once e	every 4 years)	
	101x = Rese	erved – do not	use				
hit 9-8		•0>• Alarm Val	use je Register Wi	ndow Pointer b	oits		
bit 0 0	Points to the c	orresponding Al	arm Value regis	sters when readi	ing the ALRMV	ALH and ALRM	VALL registers.
	The ALRMPT	R<1:0> value d	ecrements on e	every read or wr	ite of ALRMVA	_H until it reache	es '00'.
	ALRMVAL<1	<u>5:8>:</u>					
	00 = ALRMM	IN /D					
	10 = ALRMM	NTH					
	11 = Unimple	mented					
	<u>ALRMVAL<7:</u>	0>:					
		EC					
	10 = ALRMD	AY					
	11 = Unimple	mented					
bit 7-0	ARPT<7:0>:	Alarm Repeat	Counter Value	bits			
	11111111 =	Alarm will rep	eat 255 more t	imes			
	•						
	•						
	00000000 =	Alarm will not	repeat	nt: it is provent	od from rolling	over from OOL	to EEb upload
	CHIME = 1.		any alahin eve	n, it is prevent	.eu nom rolling		

REGISTER 19-3: ALCFGRPT: ALARM CONFIGURATION REGISTER

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
_	MINTEN2	MINTEN1	MINTEN0	MINONE3	MINONE2	MINONE1	MINONE0
bit 15							bit 8
U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
_	SECTEN2	SECTEN1	SECTEN0	SECONE3	SECONE2	SECONE1	SECONE0
bit 7							bit 0
Legend:							
R = Readable	e bit	W = Writable bit		U = Unimplem			
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cleared		x = Bit is unknown	
bit 15	Unimplement	ted: Read as '0	1				
bit 14-12	MINTEN<2:0	>: Binary Code	d Decimal Valu	ue of Minute's T	ens Digit bits		
	Contains a va	lue from 0 to 5					
bit 11-8	MINONE<3:0	>: Binary Code	ed Decimal Valu	ue of Minute's C	Ones Digit bits		
	Contains a va	lue from 0 to 9					
bit 7	7 Unimplemented: Read as '0'						
bit 6-4	it 6-4 SECTEN<2:0>: Binary Coded Decimal Value of Second's Tens Digit bits						
	Contains a value from 0 to 5.						
bit 3-0 SECONE<3:0>: Binary Coded Decimal Value of Second's Ones Digit bits							
	Contains a va	lue from 0 to 9					

REGISTER 19-10: ALMINSEC: ALARM MINUTES AND SECONDS VALUE REGISTER

To perform an A/D conversion:

- 1. Configure the A/D module:
 - a) Configure the port pins as analog inputs and/or select band gap reference inputs (ANS<12:10>, ANS<5:0>).
 - b) Select voltage reference source to match the expected range on the analog inputs (AD1CON2<15:13>).
 - c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
 - d) Select the appropriate sample/conversion sequence (AD1CON1<7:4> and AD1CON3<12:8>).
 - e) Select how conversion results are presented in the buffer (AD1CON1<9:8>).
 - f) Select the interrupt rate (AD1CON2<6:2>).
 - g) Turn on the A/D module (AD1CON1<15>).
- 2. Configure the A/D interrupt (if required):
 - a) Clear the AD1IF bit.
 - b) Select the A/D interrupt priority.

To perform an A/D sample and conversion using Threshold Detect scanning:

- 1. Configure the A/D module:
 - a) Configure the port pins as analog inputs (ANS<12:10>, ANS<5,0>).
 - b) Select the voltage reference source to match the expected range on the analog inputs (AD1CON2<15:13>).
 - c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
 - d) Select the appropriate sample/conversion sequence (AD1CON1<7:4>, AD1CON3<12:8>).
 - e) Select how the conversion results are presented in the buffer (AD1CON1<9:8>).
 - f) Select the interrupt rate (AD1CON2<6:2>).
- 2. Configure the threshold compare channels:
 - a) Enable auto-scan ASEN bit (AD1CON5<15>).
 - b) Select the Compare mode, "Greater Than, Less Than or Windowed" – CMx bits (AD1CON5<1:0>).
 - c) Select the threshold compare channels to be scanned (ADCSSH, ADCSSL).
 - d) If the CTMU is required as a current source for a threshold compare channel, enable the corresponding CTMU channel (ADCCTMUENH, ADCCTMUENL).
 - e) Write the threshold values into the corresponding ADC1BUFn registers.
 - f) Turn on the A/D module (AD1CON1<15>).

Note: If performing an A/D sample and conversion using Threshold Detect in Sleep Mode, the RC A/D clock source must be selected before entering into Sleep mode.

- 3. Configure the A/D interrupt (OPTIONAL):
 - a) Clear the AD1IF bit.
 - b) Select the A/D interrupt priority.

	-		-					
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
CH0NB2	2 CH0NB1	CH0NB0	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0	
bit 15							bit 8	
P/M/-0	P/M/-0		P/M/-0				P///_0	
CHONA:	CH0NA1	CHONA0	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0	
bit 7			01100/11	01100/10	01100/12	01100/11	bit 0	
Legend:								
R = Reada	able bit	W = Writable I	oit	U = Unimplen	nented bit, read	l as '0'		
-n = Value	at POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkn	iown	
bit 15-13	3 CH0NB<2:0>: Sample B Channel 0 Negative Input Select bits 111 = AN6 ⁽¹⁾ 110 = AN5 ⁽²⁾ 101 = AN4 100 = AN3 011 = AN2 010 = AN1 001 = AN0 000 = AVss							
DIL 12-0	000 = AVss CH0SB<4:0>: S/H Amplifier Positive Input Select for MUX B Multiplexer Setting bits 1111 = Unimplemented, do not use 1110 = AVpo 1110 = AVpo 1100 = Upper guardband rail (0.785 * VDD) 1001 = Lower guardband rail (0.215 * VDD) 1001 = Internal Band Gap Reference (VBG) ⁽³⁾ 1001-10010 = Unimplemented, do not use 10001 = No channels are connected, all inputs are floating (used for CTMU) 10000 = No channels are connected, all inputs are floating (used for CTMU) 10000 = No channels are connected, all inputs are floating (used for CTMU temperature sensor input 1011 = AN15 0110 = AN14 0110 = AN14 0101 = AN13 0110 = AN12 0011 = AN11 0100 = AN8 ⁽¹⁾ 0010 = AN8 ⁽¹⁾ 0011 = AN5 ⁽²⁾ 00100 = AN4 0011 = AN3 0010 = AN2 0010 = AN2						e sensor input)	
bit 7-5	CH0NA<2:0> The same def	CH0NA<2:0>: Sample A Channel 0 Negative Input Select bits The same definitions as for CHONB<2:0>.						
bit 4-0	CH0SA<4:0> The same def	: Sample A Cha finitions as for C	annel 0 Positiv CHONA<4:0>.	e Input Select b	oits			
Note 1: 2:	This is implement This is implement	ed on 44-pin de ed on 28-pin ar	evices only. 1d 44-pin devid	ces only.				

REGISTER 22-5: AD1CHS: A/D SAMPLE SELECT REGISTER

				Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX				
DC CH/	DC CHARACTERISTICS			mperature	-40°C ≤ -40°C ≤	2.0V to TA ≤ +8 TA ≤ +1 ≥	5 5.5V PIC24FV32KA3XX 5°C for Industrial 25°C for Extended	
Param No.	Sym	Characteristic	Min	Typ ⁽¹⁾	Мах	Units	Conditions	
	VIL	Input Low Voltage ⁽⁴⁾						
DI10		I/O Pins	Vss	—	0.2 Vdd	V		
DI15		MCLR	Vss		0.2 Vdd	V		
DI16		OSCI (XT mode)	Vss	—	0.2 Vdd	V		
DI17		OSCI (HS mode)	Vss	—	0.2 Vdd	V		
DI18		I/O Pins with I ² C™ Buffer	Vss	—	0.3 Vdd	V	SMBus is disabled	
DI19		I/O Pins with SMBus Buffer	Vss	—	0.8	V	SMBus is enabled	
	Vih	Input High Voltage ⁽⁴⁾						
DI20		I/O Pins: with Analog Functions Digital Only	0.8 Vdd 0.8 Vdd		Vdd Vdd	V V		
DI25		MCLR	0.8 Vdd		Vdd	V		
DI26		OSCI (XT mode)	0.7 Vdd	—	Vdd	V		
DI27		OSCI (HS mode)	0.7 Vdd		Vdd	V		
DI28		I/O Pins with I ² C Buffer: with Analog Functions Digital Only	0.7 Vdd 0.7 Vdd		Vdd Vdd	V V		
DI29		I/O Pins with SMBus	2.1		Vdd	V	$2.5V \le V\text{PIN} \le V\text{DD}$	
DI30	ICNPU	CNx Pull-up Current	50	250	500	μA	VDD = 3.3V, VPIN = VSS	
	lı∟	Input Leakage Current ^(2,3)						
D150		I/O Ports	_	0.05	0.1	μA	$Vss \le VPIN \le VDD$, Pin at high-impedance	
DI55		MCLR	—	—	0.1	μA	$Vss \leq V \text{PIN} \leq V \text{DD}$	
DI56		OSCI	—		5	μΑ	$\label{eq:VSS} \begin{split} &V{\sf SS} \leq V{\sf PIN} \leq V{\sf DD}, \\ &X{\sf T} \text{ and }H{\sf S} \text{ modes} \end{split}$	

TABLE 29-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Refer to Table 1-3 for I/O pin buffer types.



FIGURE 29-22: A/D CONVERSION TIMING

2: This is a minimal RC delay (typically 100 ns) which also disconnects the holding capacitor from the analog input.

AC CHARACTERISTICS			Standard Operating Conditions:1.8V to 3.6V PIC24F32KA3XX2.0V to 5.5V PIC24FV32KA3XXOperating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for Extended					
Param No.	Symbol	Characteristic	Min.	Тур	Max.	Units	Conditions	
		(Clock Pa	rameter	s			
AD50	Tad	A/D Clock Period	600	—	—	ns	Tcy = 75 ns, AD1CON3 in default state	
AD51	TRC	A/D Internal RC Oscillator Period	-	1.67	—	μs		
			Convers	ion Rate)			
AD55	TCONV	Conversion Time	_	12 14	_	Tad Tad	10-bit results 12-bit results	
AD56	FCNV	Throughput Rate			100	ksps		
AD57	TSAMP	Sample Time	_	1	_	Tad		
AD58	TACQ	Acquisition Time	750	—	—	ns	(Note 2)	
AD59	Tswc	Switching Time from Convert to Sample	-	-	(Note 3)			
AD60	TDIS	Discharge Time	12	_	—	TAD		
		(Clock Pa	rameter	s			
AD61	TPSS	Sample Start Delay from Setting Sample bit (SAMP)	2	—	3	Tad		

TABLE 29-41: A/D CONVERSION TIMING REQUIREMENTS⁽¹⁾

Note 1: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

2: The time for the holding capacitor to acquire the "New" input voltage when the voltage changes full scale after the conversion (VDD to Vss or Vss to VDD).

3: On the following cycle of the device clock.









44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	N	IILLIMETER	S	
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		44	
Pitch	е		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated

3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension. usually without tolerance. for information purposes only.

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